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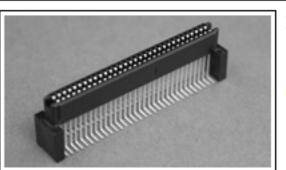


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2007042-4 Product Details

Industries



2007042-4

TE Internal Number: 2007042-4

Active

1 mm Free Height (IEEE 1386)

About TE



Support Center

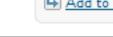
Product Highlights:

- Connector Style = Receptacle
- 64 Positions

Resources

- Stack Height = 14.00 mm, 15.00 mm
- Without PCB Mount Retention
- With PCB Mount Alignment

View all Features









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Documentation & Additional Information

Product Drawings:

RECEPTACLE ASSY, W/ VACUUM COVER, 1.0mm FH(IEEE 1386... (PDF, English)

Catalog Pages/Data Sheets:

None Available

Product Specifications:

None Available

Application Specifications:

None Available

Instruction Sheets:

None Available

CAD Files:

None Available

Additional Product Images:

Product Photo

Related Products:

Tooling

Product Features (Please use the Product Drawing for all design activity)

Product Type Features:

- PCB Mount Retention = Without
- PCB Mount Alignment = With
- Product Type = Connector
- Connector Type = Connector Assembly
- Product Line = 1mm FH

Electrical Characteristics:

Contact - Rated Current (A) = 0.8

Termination Features:

Tail Length (mm [in]) = 2.05 [0.081]

Body Features:

- Number of Positions = 64
- Number of Columns = 32
- Centerline (mm [in]) = 1.00 [0.039]
- Underplate Material Thickness (µm [µin]) = 1.27 [50.000]

Contact Features:

- Contact Base Material = Phosphor Bronze
- Contact Plating, Mating Area, Material = Gold
- Contact Plating, Mating Area, Thickness (μm [μin]) = 1.27 [50]
- Tail Plating Material = Tin-Lead
- Tail Plating, Thickness (μm [μin]) = 3.81 [150]
- Underplate Material = Nickel

Housing Features:

<u>List all Documents</u>

Connector Style = Receptacle

Configuration Features:

Stack Height (mm [in]) = 14.00 [0.551], 15.00 [0.591]

Industry Standards:

- RoHS/ELV Compliance = ELV compliant, 5 of 6 Compliant
- Lead Free Solder Processes = Not suitable for lead free processing

Conditions for Usage:

- Applies To = Printed Circuit Board
- Board-to-Board Configuration = Mezzanine

Operation/Application:

- Pick and Place Cover = With
- Application Use = Board-to-Board
- Contact Transmits (Typical Application) = Signal (Data)

Other:

Brand = AMP

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